



General Description

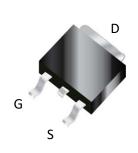
These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

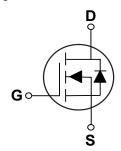
BV _{DSS}	R _{DS(ON)}	Ι _D
80 V	3.2 mΩ	180 A

Features

- $R_{DS(ON)} \le 3.2 m\Omega @V_{GS} = 10V$
- · Improved dv/dt capability
- Fast switching
- · Green Device Available

TO-263 Pin Configuration





Applications

- Networking
- · Load Switch
- · LED applications
- · Quick Charger

Absolute Maxim	um Ratings T _C =25°C unless otherwise noted		
Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	80	V
V_{GS}	Gate-Source Voltage	+20 / -12	V
1	Drain Current - Continuous (T _C =25°C)	180	Α
I _D	Drain Current - Continuous (T _C =100°C)	114	7
I _{DM}	Drain Current - Pulsed (NOTE 1)	720	Α
EAS	Single Pulse Avalanche Energy (NOTE 2)	660	mJ
IAS	Single Pulse Avalanche Current (NOTE 2)	115	Α
D	Power Dissipation (T _C =25°C)	278	W
P_{D}	Power Dissipation - Derate above 25°C	2.22	W/°C
T _J	Operating Junction Temperature Range	-50 to 150	°C
T _{STG}	Storage Temperature Range	-50 to 150	°C
Marking Code		NK3P2	

Thermal Characteristics					
Symbol	mbol Parameter Typ. Max.		Unit		
$R_{\theta JA}$	Thermal Resistance Junction to Ambient		62	°C/W	
$R_{\theta JC}$	Thermal Resistance Junction to Case		0.45	°C/W	





Electrical Characteristics (T_J=25°C, unless otherwise noted)

Off Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =250uA	80			V
I _{DSS}	IDrain-Source Leakage Current	V_{DS} =80V , V_{GS} =0V , T_{J} =25 $^{\circ}$ C			1	uA
		V_{DS} =64V , V_{GS} =0V , T_{J} =85 $^{\circ}$ C			10	uA
I _{GSS}	Gate-Source Leakage Current	V_{GS} =20V , V_{DS} =0V			100	nA

On Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
R _{DS(ON)}	Static Drain-Source On-Resistance	V _{GS} =10V , I _D =30A			3.2	mΩ
		V _{GS} =4.5V , I _D =20A			4.6	
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}$, $I_D=250uA$	1.0		2.5	V
gfs	Forward Transconductance	V_{DS} =10V , I_{D} =3A		20		S

Dynamic and switching Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Q_g	Total Gate Charge	V _{DS} =40V , V _{GS} =10V , I _D =20A		138		
Q_gs	Gate-Source Charge	$-(NOTE 3 \cdot 4)$		22.4		nC
Q_gd	Gate-Drain Charge	(10012 3 - 4)		35.1		
$T_{d(on)}$	Turn-On Delay Time	V_{DD} =40V , V_{GS} =10V , R_{G} =1 Ω , I_{D} =1A (NOTE 3 \ 4)		17.2		
T_r	Rise Time			18		nS
$T_{d(off)}$	Turn-Off Delay Time			76		113
T_f	Fall Time			84.4		
C _{iss}	Input Capacitance	V _{DS} =40V , V _{GS} =0V , f=1MHz		7036		
C _{oss}	Output Capacitance			1490		pF
C _{rss}	Reverse Transfer Capacitance			86		
R_g	Gate Resistance	V_{DS} =0V , V_{GS} =0V , f=1MHz		1.94		Ω

Drain-Source Diode Characteristics and Ratings

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Is	Continuous Source Current	V_G = V_D = $0V$,Force Current			180	Α
I _{SM}	Pulsed Source Current				360	Α
V_{SD}	Diode Forward Voltage	V_{GS} =0V , I_{S} =1A , T_{J} =25 $^{\circ}$ C			1	V
trr	Reverse Recovery Time	I _S =10A , di/dt=100A/μs , T _J =25°C -		73.2		nS
Qrr	Reverse Recovery Charge			170.7		nC

NOTES:

- ${\bf 1.}\ Repetitive\ Rating: Pulsed\ width\ limited\ by\ maximum\ junction\ temperature.$
- 2. V_{DD} =25V, V_{GS} =10V, L=0.1mH, I_{AS} =115A, R_{G} =25 Ω , Starting T_{J} =25 $^{\circ}$ C.
- 3. The data tested by pulsed , pulse width \leq 300us , duty cycle \leq 2%.
- ${\bf 4.} \ Essentially \ independent \ of \ operating \ temperature.$





Characteristics Curves

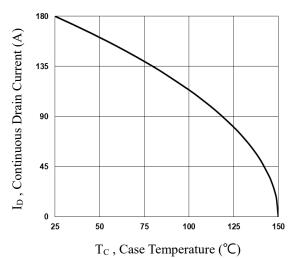


Fig.1 Continuous Drain Current vs. Tc

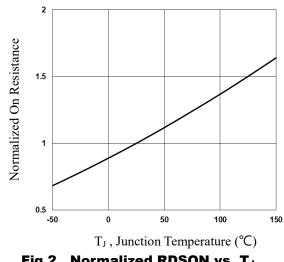


Fig.2 Normalized RDSON vs. TJ

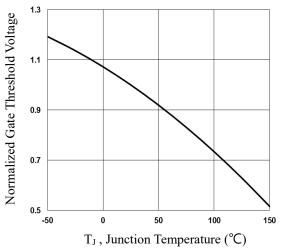


Fig.3 Normalized Vth vs. T_J

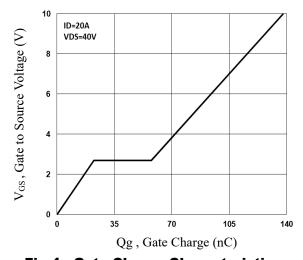
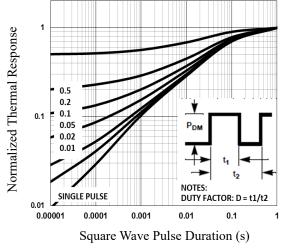


Fig.4 Gate Charge Characteristics



Normalized Transient Impedance

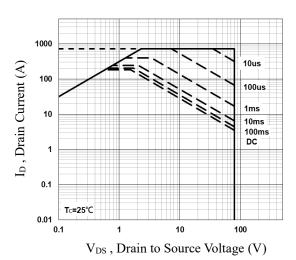
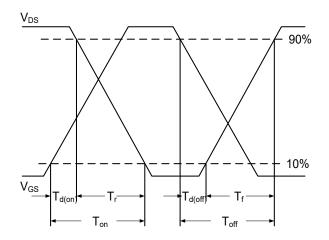


Fig.6 Maximum Safe Operation Area





Characteristics Curves



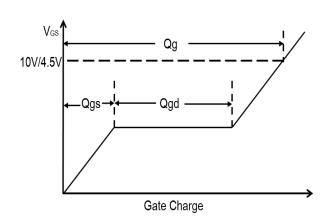
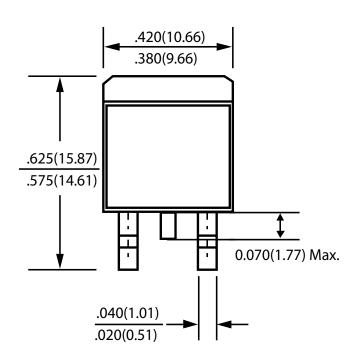
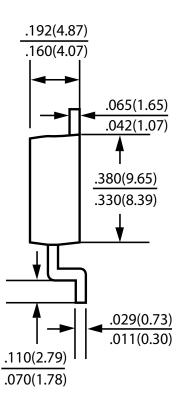


Fig.7 Switching Time Waveform

Fig.8 Gate Charge Waveform

Package Outline Dimensions





TO-263Dimensions in inches and (millimeters)





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